APPROVAL SHEET

To：

Customer P/N：

UDE P/N： SBA0-ZZ-0009

Description： SFP28 2X1 Ass'y

Press-Fit

Contact Area : 30μ" Min. Gold

With Lightpipe

SFP28 25G(NRZ), SFP56 50G(PAM4)

Packing With Tray

RoHS

Spec No.	Update Date	Revision
SBA021013-00	2021/6/9	A

Approved	Checked	Prepared

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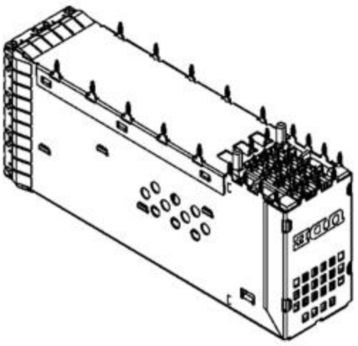
Revision History

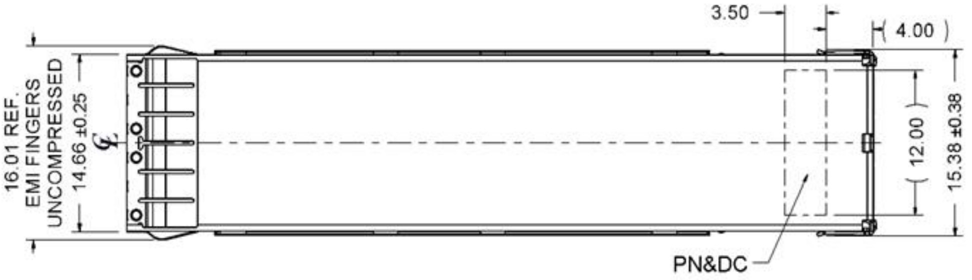
Issue Date	Revision	Comments	Operator
2021/6/9	A	Initial Release .	Jaime

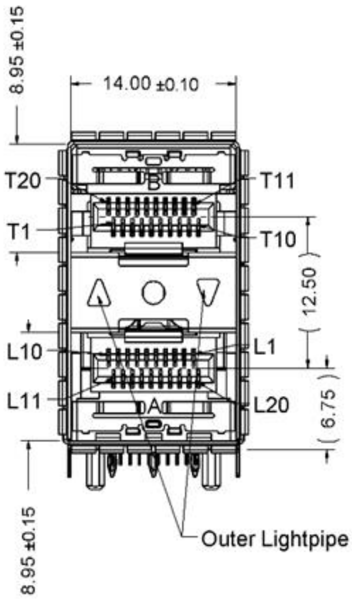
1. MECHANICAL DIMENSION

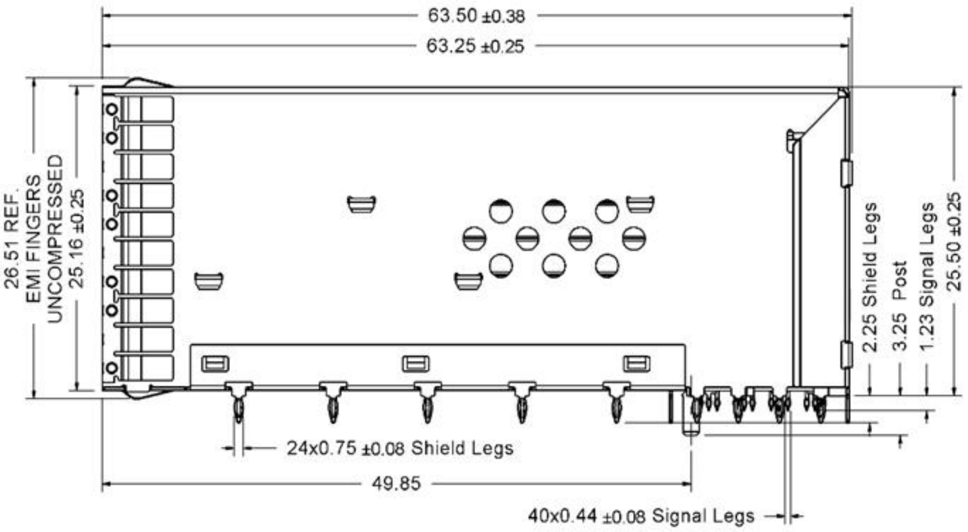
Product Dimension

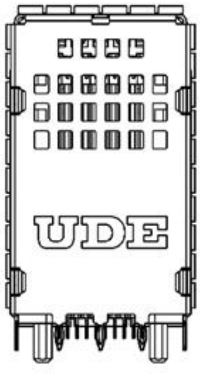
Unit:mm	General Tolerance :	X.X : ± 0.38 X.XX : ± 0.20



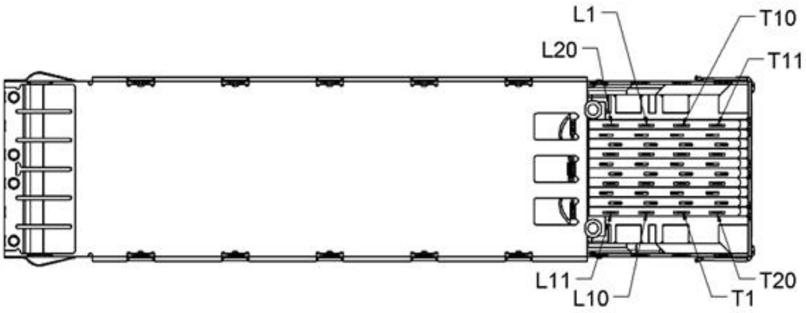








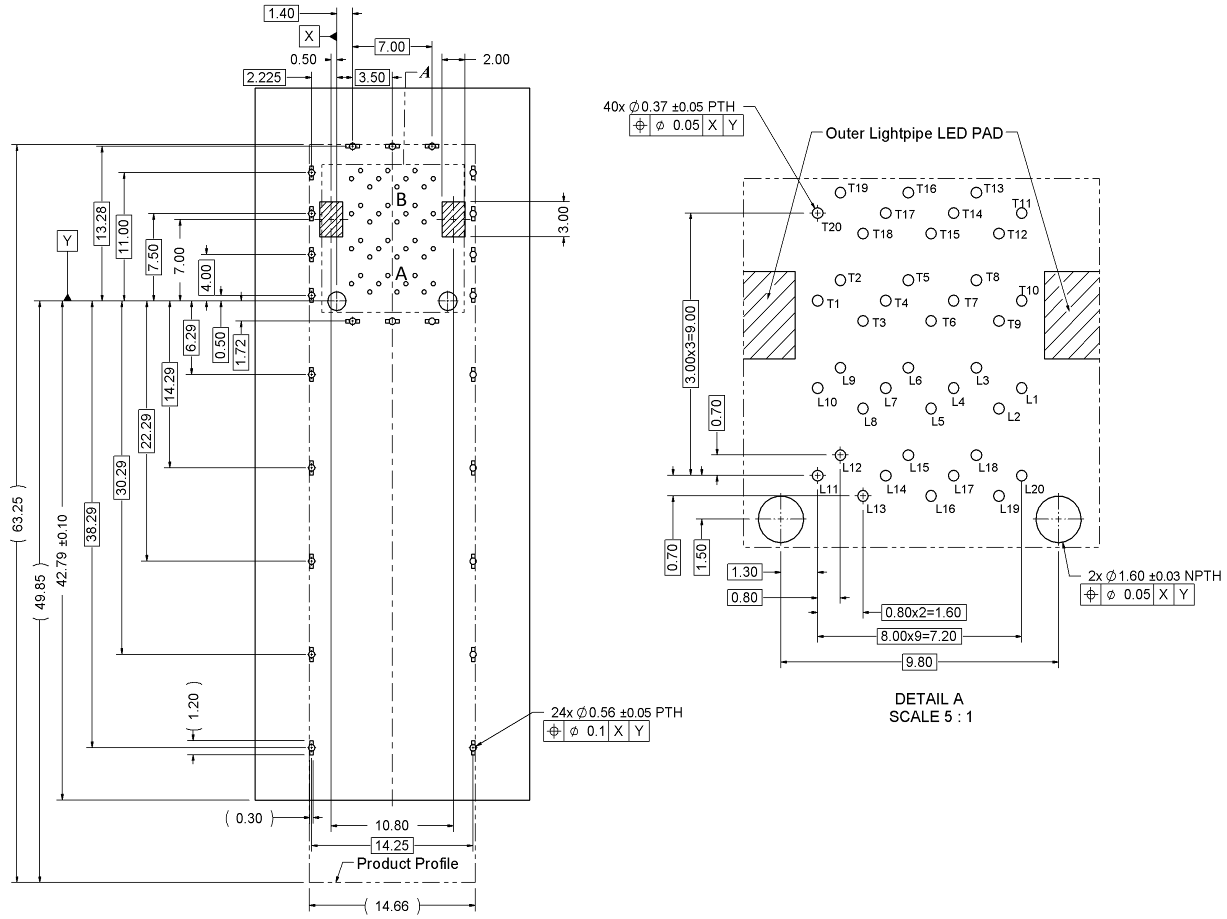
RIGHT VIEW



2. Recommended PCB Layout.Component Side of Board

All dimension units are "mm".

All dimension tolerances are ±0.05mm unless otherwise specified



DETAIL A
SCALE 5 : 1

NOTES:

1.PADS AND VIAS CONNECT TO CHASSIS GROUND

RECOMMEND PADS TO BE 2.00mm SQUARE

2.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.

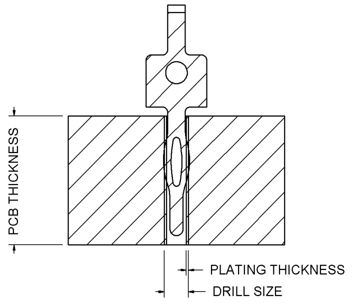
Table1

Layout / Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

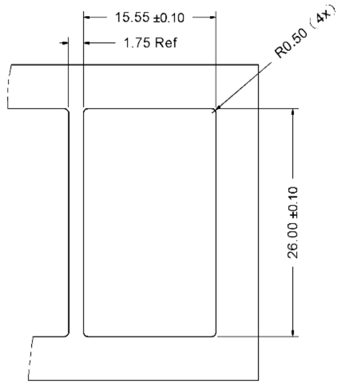
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

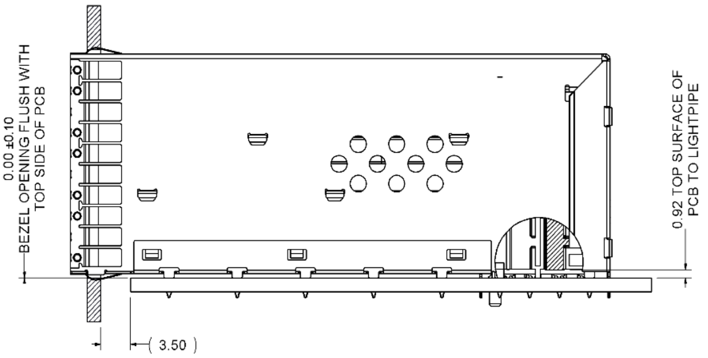
PLATED THROUGH HOLE	0.56 SHIELD PINS	0.37 SIGNAL PINS
FINISHED HOLE DIAMETER	0.56 ±0.05	0.37 ±0.05
DRILLED HOLE DIAMETER	0.66	0.47
COPPER PLATING	0.025 min.	0.025 min.



RECOMMENDED MOTHER BOARD
THROUGH HOLE DIMENSION

3. Recommended Panel cutout





PRESS-FIT ASSEMBLIES
Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool
Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
2X1	Copper w/OSP	440±50N

4. Packing Information

24 pcs finished goods per tray

5 trays(120pcs finished goods) per master carton

5. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Terminal : Copper Alloy,Thickness=0.20mm
Finish : 30µ" min Gold Plating on contact area,50µ" min.Nickel overall
Solder Tail : 30µ" min Matte Tin,50µ" min Nickel overall
Top Shell : Copper Alloy, Thickness=0.25mm
Bottom Shell : Copper Alloy, Thickness=0.25mm
UD Mid Ground : Copper Alloy, Thickness=0.25mm
EMI Spring Finger : Ph.Bronze, Thickness=0.08mm
EMI Spring Finger：30u" min.Nickel overall
Inner Spring : SUS304, Thickness=0.20mm
Connector Housing: LCP, Black<UL94V-0>
Lightpipe Cover：PBT,Black<UL94V-0>
Light Pipe : PC, Transparent <UL94V-0>

6. Operating and Storage Temperature

Operating Temperature :	-40°C to +85°C
Storage Temperature :	-55°C to +105°C

7. SFP 1X Connector specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 1000MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

8. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

9. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage,corrosion and deterioration during shipment and storage.